

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT7509110

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JEROME TEYSSEYRE	11/02/2020
INPIL YOO	11/20/2020
JOOYANG EOM	11/16/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Street Address:</b>	5005 E. MCDOWELL ROAD
<b>Internal Address:</b>	MAILDROP A700
<b>City:</b>	PHOENIX
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17822844
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	6022443574
<b>Email:</b>	patents@onsemi.com
<b>Correspondent Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Address Line 1:</b>	5005 E. MCDOWELL ROAD
<b>Address Line 2:</b>	MAILDROP A700
<b>Address Line 4:</b>	PHOENIX, ARIZONA 85008
<b>ATTORNEY DOCKET NUMBER:</b>	ONS04079D01US
<b>NAME OF SUBMITTER:</b>	SHARRON CASTILLO
<b>SIGNATURE:</b>	/Sharron Castillo/
<b>DATE SIGNED:</b>	08/29/2022
<b>Total Attachments: 5</b>	
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For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name \_\_\_\_\_ of (City and State OR Country) \_\_\_\_\_

**JEROME TEYSSEYRE**

**SCOTTSDALE, ARIZONA**

**INPIL YOO**

**UNTERHACHING GERMANY (FEDERAL REPUBLIC OF)**

**JOOYANG EOM**

**GIMPO-SI KOREA, REPUBLIC OF (KR)**

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

**Title: POWER MODULE PACKAGE FOR DIRECT COOLING MULTIPLE POWER MODULES**

**Attorney Docket No.: ONS04079US**

**Serial No.:** 16/949896

**Filing Date:** November 19, 2020


together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature):  \_\_\_\_\_  
**Jerome Teysseyre**

Signed on this 02 day of November, 2020  
day month year

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By (Inventor signature): \_\_\_\_\_  
**Inpil Yoo**

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

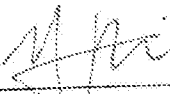
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By (Inventor signature): \_\_\_\_\_  
**JooYang Eom**

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

By (inventor signature): \_\_\_\_\_  
Jerome Teysseyre

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

By (inventor signature):  \_\_\_\_\_  
Inpil Yoo

Signed on this 20 day of November, 2020  
day month year

By (inventor signature): \_\_\_\_\_  
JooYang Eom

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

ASSIGNMENT & AGREEMENT  
ONS04078US

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we:

Name: \_\_\_\_\_ of (City and State OR Country): \_\_\_\_\_

JEROME TEYSSEYRE SCOTTSDALE, ARIZONA  
INPH YOO UNTERHACHING GERMANY (FEDERAL REPUBLIC OF)  
JOOYANG EOM SHIPO-SI KOREA, REPUBLIC OF (KR)

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in:

Title: POWER MODULE PACKAGE FOR DIRECT COOLING MULTIPLE POWER MODULES  
Attorney Docket No.: ONS04078US  
Serial No.: 16/945896  
Filing Date: November 19, 2020

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, re-examinations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

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ASSIGNMENT & AGREEMENT  
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By (inventor signature) \_\_\_\_\_  
Jerome Teyssieys

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

By (inventor signature) \_\_\_\_\_  
Inpil Yoo

Signed on this \_\_\_\_\_ day of \_\_\_\_\_, 2020  
day month year

By (inventor signature) \_\_\_\_\_  
JaeYang Kim

Signed on this 15 day of Nov, 2020  
day month year